 Qualified for Automotive Applications Operating Range 2-V to 5.5-V V_{CC} 	_	PACKAGE VIEW)
 Unbuffered Outputs 	1A [1	J ₁₄ V _{CC}
 Latch-Up Performance Exceeds 250 mA Per JESD 17 	1Y 🛮 2 2A 🗓 3	13 6A 12 6Y
 ESD Protection Exceeds JESD 22 2000-V Human-Body Model (A114-A) 	2Y 🛮 4 3A 🖟 5	11 5A 10 5Y
 200-V Haman-Body Model (A115-A) 200-V Machine Model (A115-A) 1000-V Charged-Device Model (C101) 	3Y [6 GND [7	9 4A 8 4Y

description/ordering information

The SN74AHCU04 device contains six independent inverters. This device performs the Boolean function $Y = \overline{A}$. Internal circuitry consists of single-stage inverters that can be used in analog applications such as crystal oscillators.

ORDERING INFORMATION[†]

TA	PACKA	GE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Tape and reel	SN74AHCU04QDRQ1	AHCU04Q
-40 C to 125°C	TSSOP - PW	Tape and reel	SN74AHCU04QPWRQ1	AHCU04Q

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Note 1)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	V
		V _{CC} = 2 V	1.7		
ViH	High-level input voltage	V _{CC} = 3 V	2.4		V
		$V_{CC} = 5.5 \text{ V}$	4.4		
		$V_{CC} = 2 V$		0.3	
V _{IL} Low-level input voltage	Low-level input voltage	V _{CC} = 3 V		0.6	V
		V _{CC} = 5.5 V		1.1	
٧ı	Input voltage		0	5.5	V
VO	Output voltage		0	Vcc	V
		V _{CC} = 2 V		-50	μΑ
IOH	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	4
		$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V _{CC} = 2 V		50	μΑ
lOL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4	
			8	mA	
TA	Operating free-air temperature		-40	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	T	T _A = 25°C			T _A = -40°C TO 125°C		T _A = -40°C TO 85°C	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
		2 V	1.8	2		1.8		1.8		
	I _{OH} = -50 μA	3 V	2.7	3		2.7		2.7		
VOH		4.5 V	4	4.5		4		4		V
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.3		2.4		
	I _{OH} = -8 mA	4.5 V	3.94			3.5		3.65		
		2 V			0.2		0.2		0.2	
	I _{OL} = 50 μA	3 V			0.3		0.3		0.3	
VOL		4.5 V			0.5		0.5		0.5	V
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
II	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	·	20	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		2	10	·		·	10	pF

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	LOAD CAPACITANCE	T	λ = 25°C	;	T _A = -		T _A = -		UNIT			
	(INPUT)	(001F01)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX				
tPLH .	^	V	0. 45 = 5		5	7.1	1	10.5	1	8.5				
^t PHL	А	<u> </u>	Y	Y $C_L = 15 pF$	Ť	CL = 15 pF		5	7.1	1	10.5	1	8.5	ns
^t PLH	۸		C _I = 50 pF		7.5	10.6	1	14	1	12	20			
t _{PHL}	А	ī	CL = 50 pr		7.5	10.6	1	14	1	12	ns			

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	LOAD	T	λ = 25°C	;	T _A = -		T _A = -4		UNIT			
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX				
tPLH	•	V	0 45 -5		3.5	5.5	1	8.5	1	6.5				
^t PHL	А	ī	ī	Y CL = 15 pF	ı	C _L = 15 pF		3.5	5.5	1	8.5	1	6.5	ns
t _{PLH}	А	~	C _I = 50 pF	·	5	7	1	11	1	9	ns			
^t PHL	Α	· '	CL = 50 pr		5	7	1	11	1	9	115			

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noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.5		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.5		V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		4.3		V
V _{IH(D)}	High-level dynamic input voltage	4			V
V _{IL(D)}	Low-level dynamic input voltage			1	V

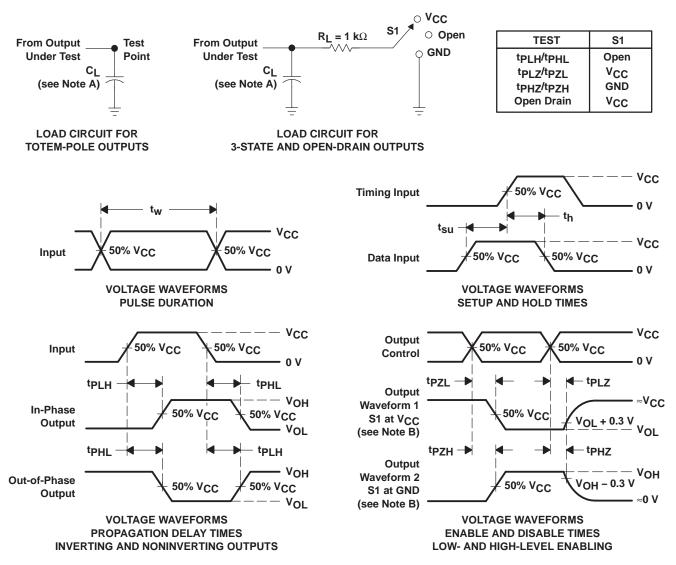
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	7.3	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns. $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHCU04QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCU04QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74AHCU04-Q1:

Catalog: SN74AHCU04

Enhanced Product: SN74AHCU04-EP

• Military: SN54AHCU04

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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